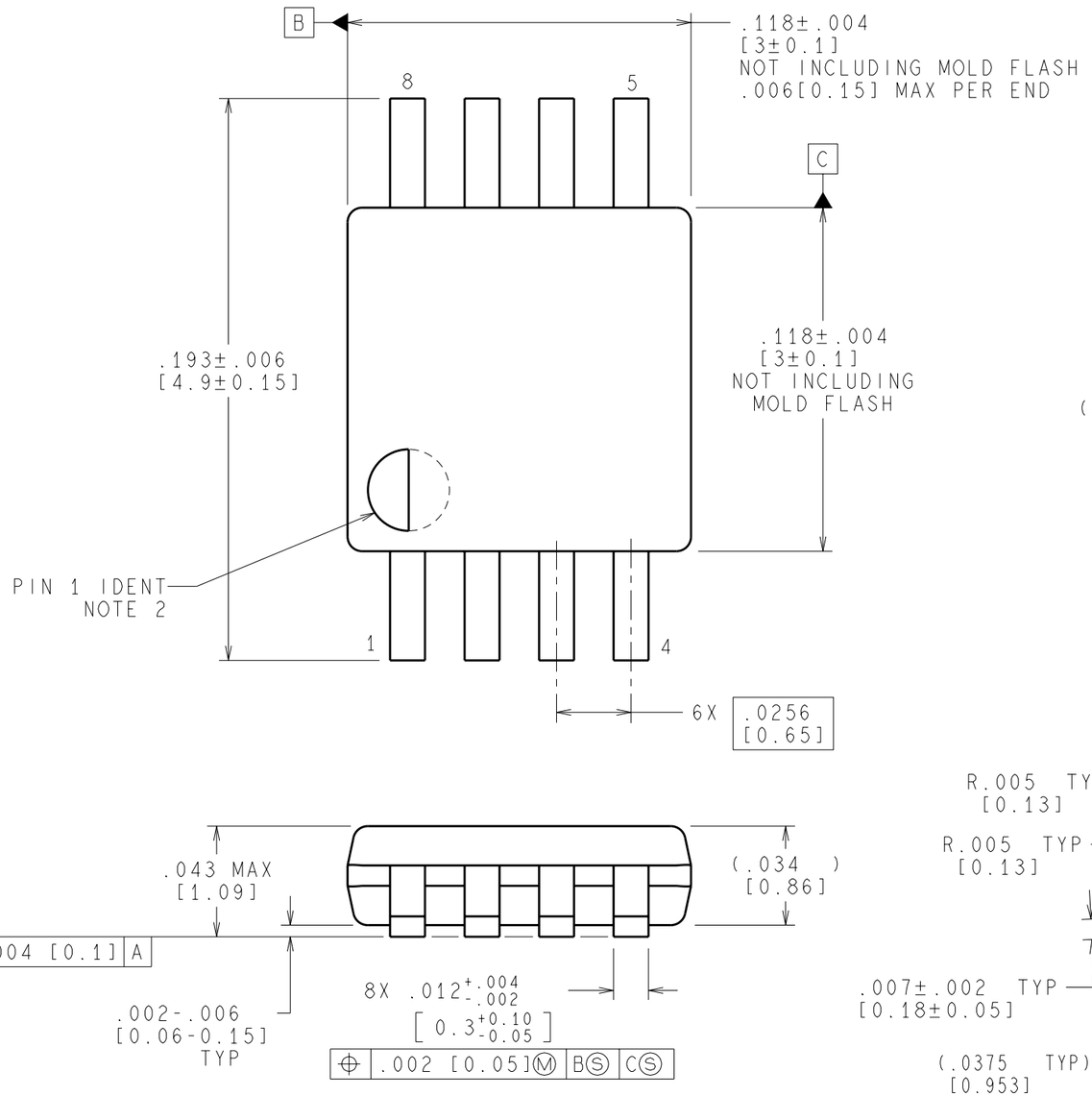
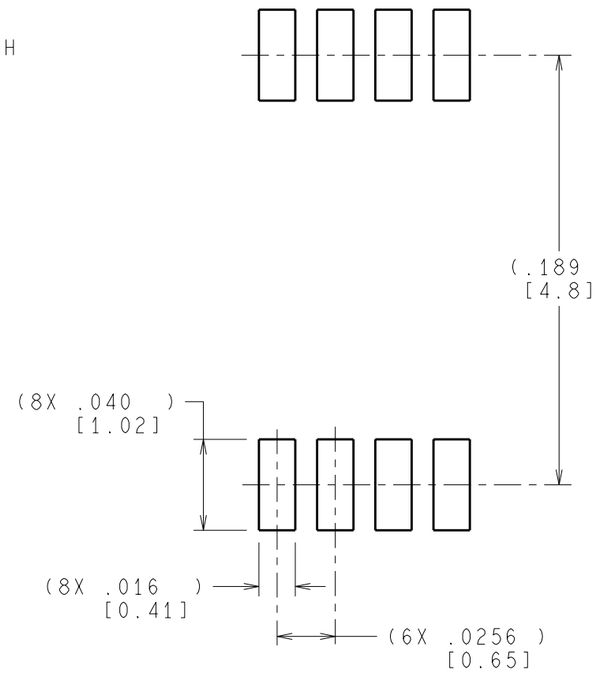
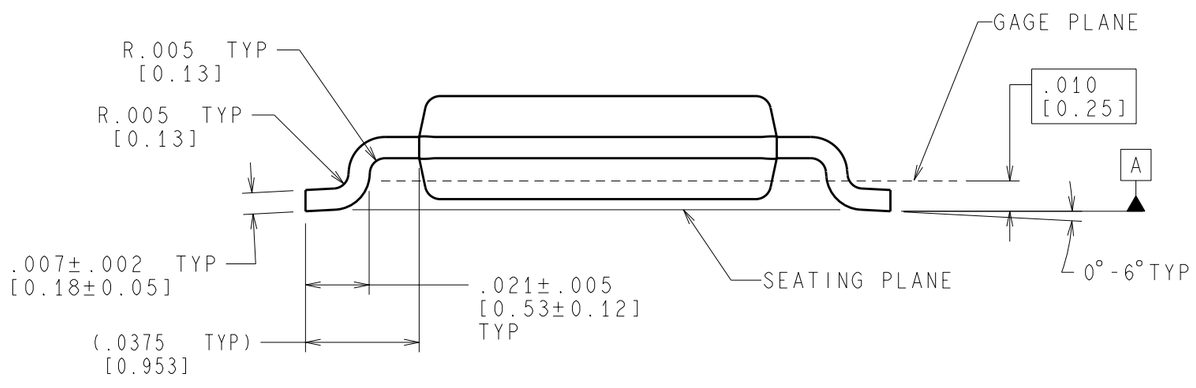
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11620	11/18/1996	TL/FL
B	DIM .043 MAX WAS .030-.037; DIM (.034) WAS (.033); DIM .193±.006 WAS .193±.004	11634	01/07/1997	MS/FL
C	COPLANARITY .004[0.1] WAS .002[0.05]; NOTE 1: 200 WAS 150, 5.08 WAS 3.81	11932	02/24/1998	MS/CD
D	DIM .043 MAX WAS .034	12170	03/12/1999	MS/CD
E	UPDATE DWG TO CURRENT STD'S; REVISE NOTE 1; UPDATE TITLE & NOTE 2; CHANGE TO B SIZE FORMAT.	1015	04/29/2003	MS/RW
F	ADD MOLD FLASH NOTE TO BODY DIM'S .118	2508	04/04/2008	TL/RW





参考資料

RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. PIN 1 IDENTIFICATION TO HAVE HALF OR FULL CIRCLE OPTION.
3. REFERENCE JEDEC REGISTRATION MO-187, VARIATION AA.

CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

APPROVALS	DATE
DRAWN T. LEQUANG	11/18/1996
DFTG. CHK. KURT SINCERBOX	04/04/2008
ENGR. CHK. RANDALL WALBERG	04/04/2008

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

MINI SOIC,
.118x.118x.034in,
8 LD, .0256in PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-MUA08A	F

FORMERLY: N/A

SHEET 1 of 1